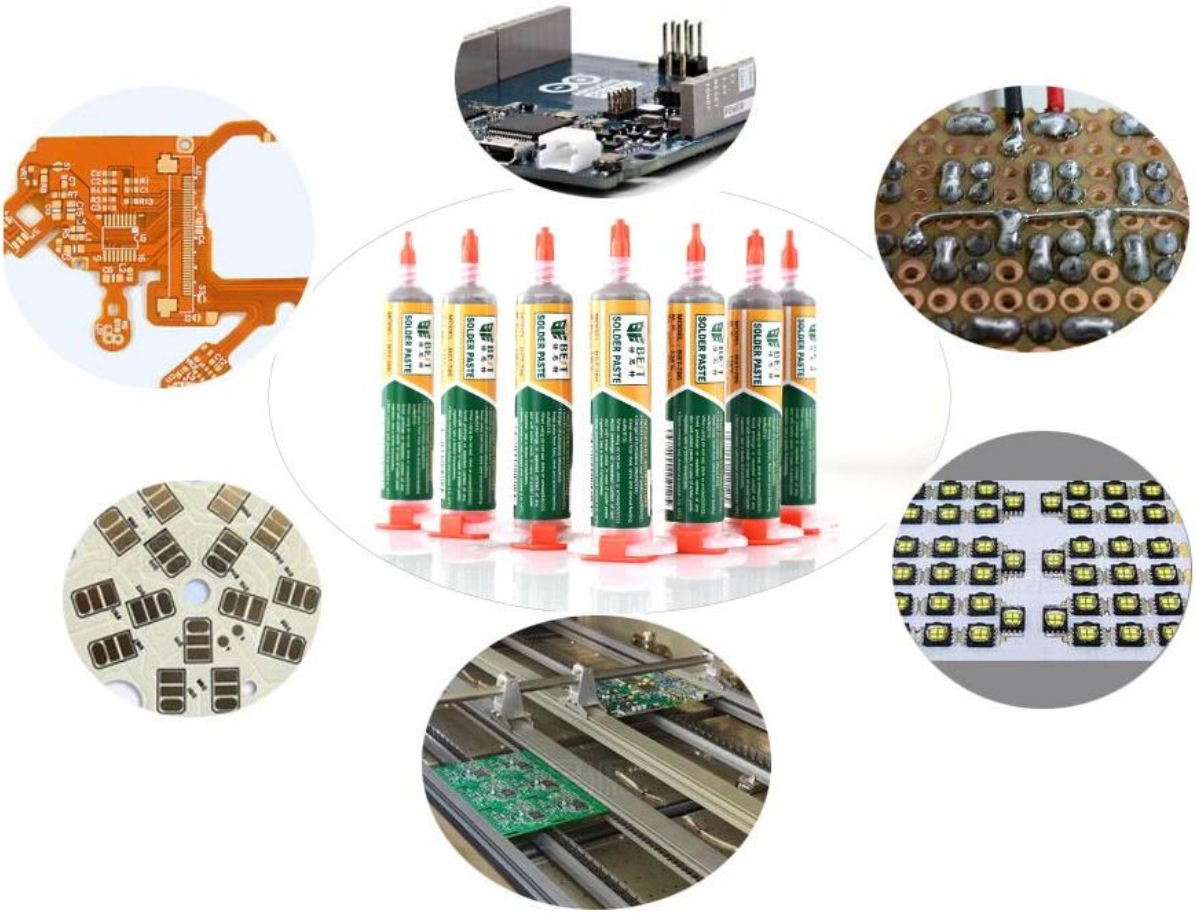
100% novo e de alta qualidade!!
O fluxo de resina é usado para facilitar a soldagem.
Limpa e previne a oxidação de metais, o que permite que a solda crie ligações mecânicas e elétricas fortes e duradouras.
Atua também como agente umectante, aumentando o fluxo de solda e a eficiência do processo de soldagem.
Perfeito para telefones celulares, placas de PC e outras soldagens de fluxo de nível de chip eletrônico sofisticado.
Especificações
Produto: BST-706
Ponto de fusão: 138 ℃
Volume: 10cc
Peso: 38g
Ingredientes: Sn99%, Cu0.7%, Ag0.3%

PRODUCT USAGE

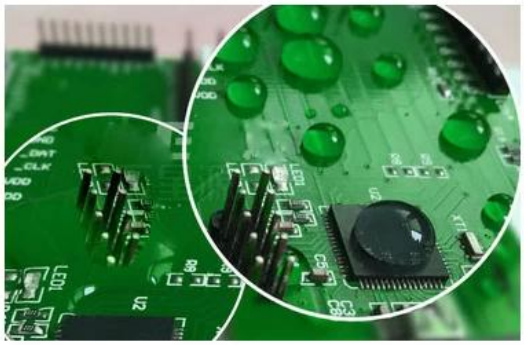


PRODUCT SIZE

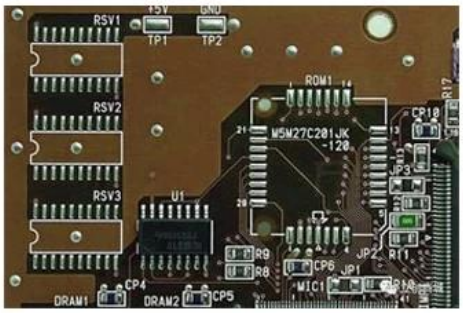
M. P. : 138°C
Sn : 99%
Cu : 0.7%
Ag : 0.3%
Volume : 10cc
MADE IN CHINA

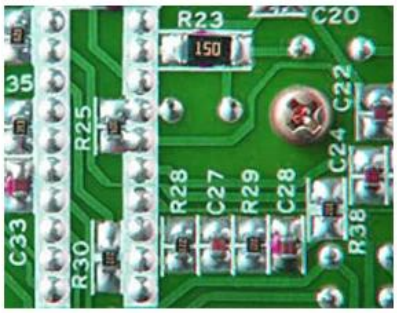
Brand: BEST	Model Number:706
Melting point:138℃	Ingredients：Sn99% Cu0.7% Ag0.3%
Volume:10cc	Weight：38g

Having a large insulation resistance does not corrode the PCB, and the requirements for no-cleaning can be achieved.



High impedance, full and bright solder, low residue





PRODUCT PHOTOGRAPH

SOLDER PASTE
SOLDER PASTE
SOLDER PASTE
SOLDER PASTE
SOLDER PASTE